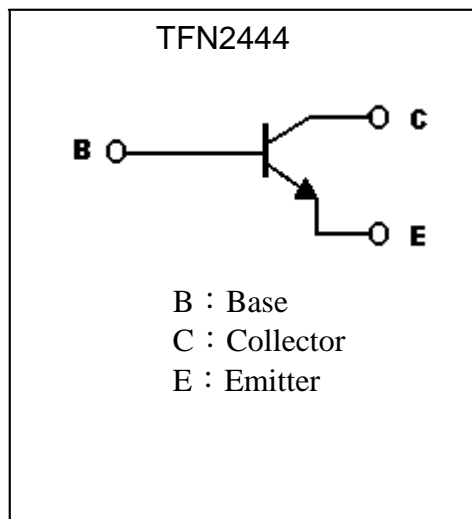


TFN2444

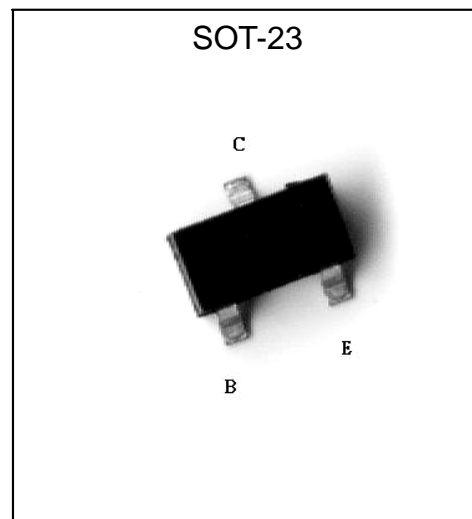
Features

- The TFN2444 is designed for general purpose low frequency power amplifier applications.
- Low $V_{CE(sat)}$, $V_{CE(sat)}=40mV$ (typical), at $I_C / I_B = 50mA / 2.5mA$
- Complementary to BTB1590N3
- Pb-free package

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	40	V
Collector-Emitter Voltage	V_{CEO}	25	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current (DC)	I_C	800	mA
Collector Current (Pulse)	I_{CP}	1.5 (Note)	A
Power Dissipation	P_d	225	mW
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	-55~+150	°C

Note : Single pulse, $P_w=10ms$



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	40	-	-	V	$I_C=100\mu A, I_E=0$
BV_{CEO}	25	-	-	V	$I_C=2mA, I_B=0$
BV_{EBO}	6	-	-	V	$I_E=100\mu A, I_C=0$
I_{CBO}	-	-	0.5	μA	$V_{CB}=30V, I_E=0$
I_{EBO}	-	-	0.5	μA	$V_{EB}=6V, I_C=0$
* $V_{CE(sat)1}$	-	40	60	mV	$I_C=50mA, I_B=2.5mA$
* $V_{CE(sat)1}$	-	0.15	0.3	V	$I_C=400mA, I_B=20mA$
* $V_{CE(sat)2}$	-	0.25	0.5	V	$I_C=800mA, I_B=80mA$
* $V_{BE(on)}$	-	-	1	V	$V_{CE}=1V, I_C=10mA$
* h_{FE1}	180	-	820	-	$V_{CE}=1V, I_C=100mA$
* h_{FE2}	40	-	-	-	$V_{CE}=1V, I_C=600mA$
f_T	-	150	-	MHz	$V_{CE}=5V, I_C=50mA, f=100MHz$
Cob	-	15	-	pF	$V_{CB}=10V, f=1MHz$

*Pulse Test : Pulse Width $\leq 380\mu s$, Duty Cycle $\leq 2\%$

Classification Of h_{FE1}

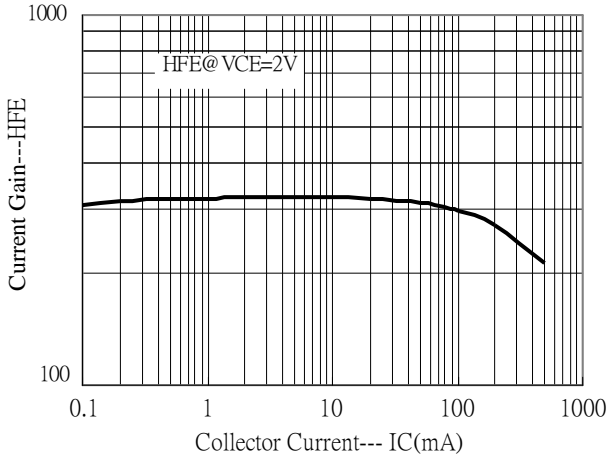
Rank	R	S	T
Range	180~390	270~560	390~820

Ordering Information

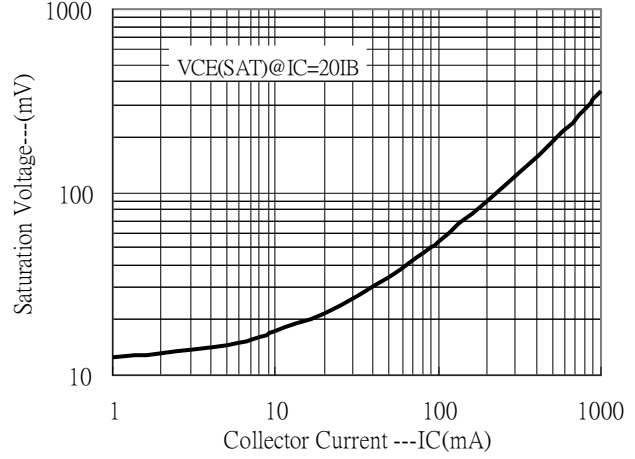
Device	Package	Shipping	Marking
TFN2444	SOT-23 (Pb-free)	3000 pcs / Tape & Reel	BS

Characteristic Curves

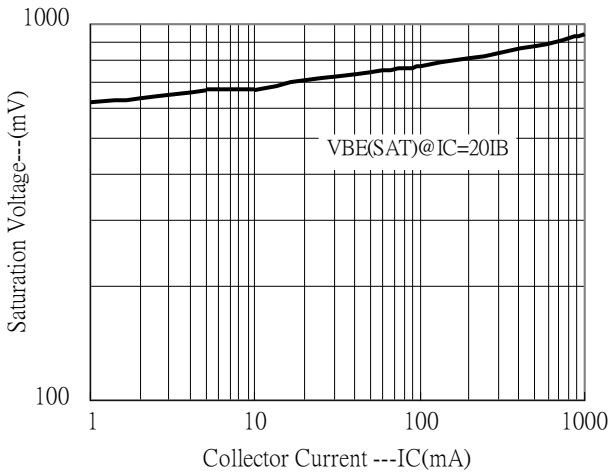
Current Gain vs Collector Current



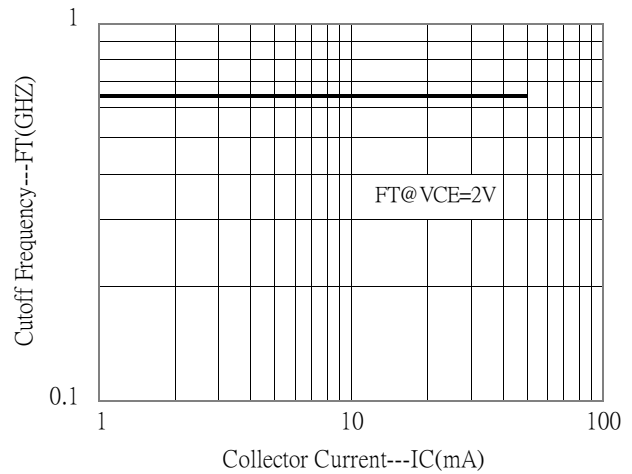
Saturation Voltage vs Collector Current



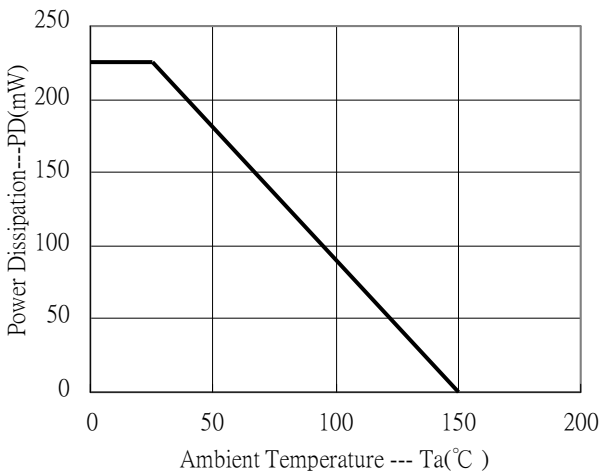
Saturation Voltage vs Collector Current



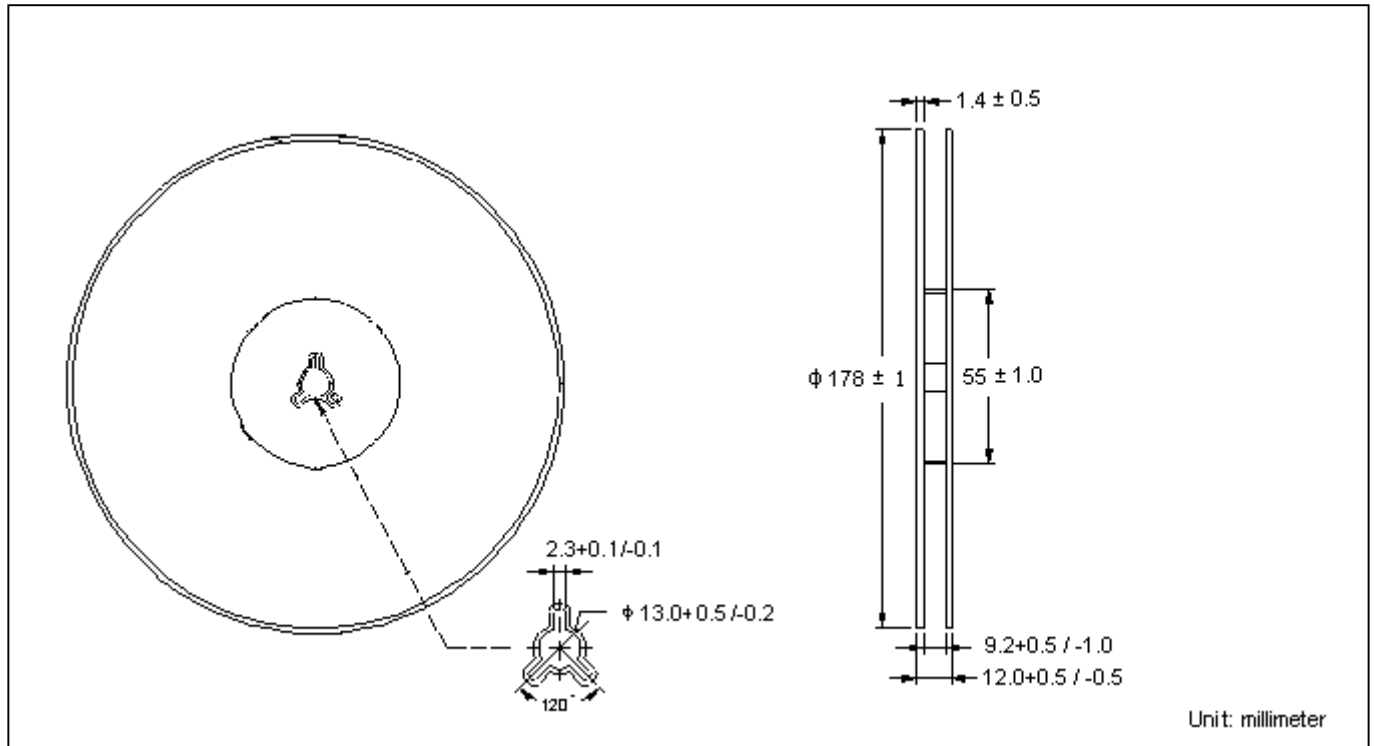
Cutoff Frequency vs Collector Current



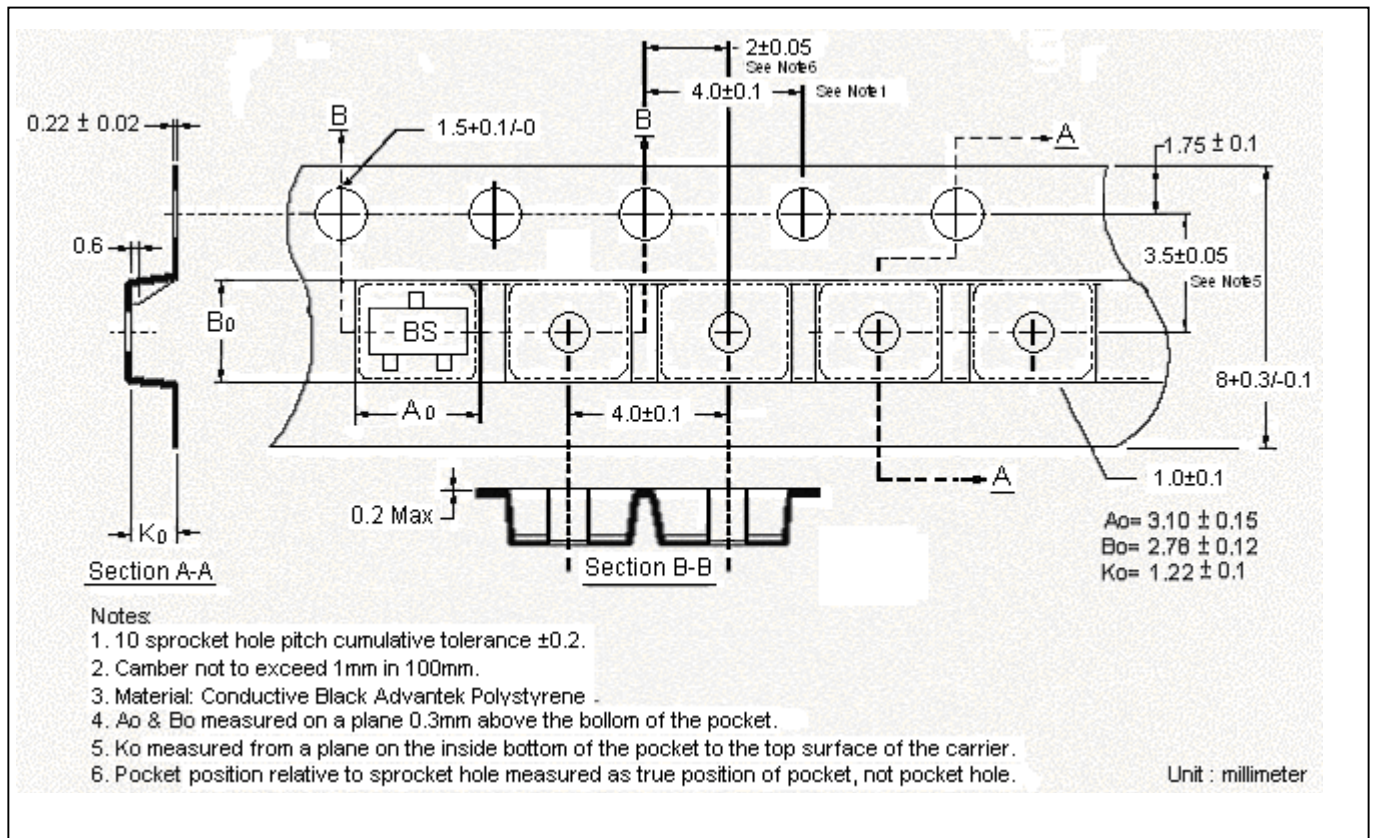
Power Derating Curve



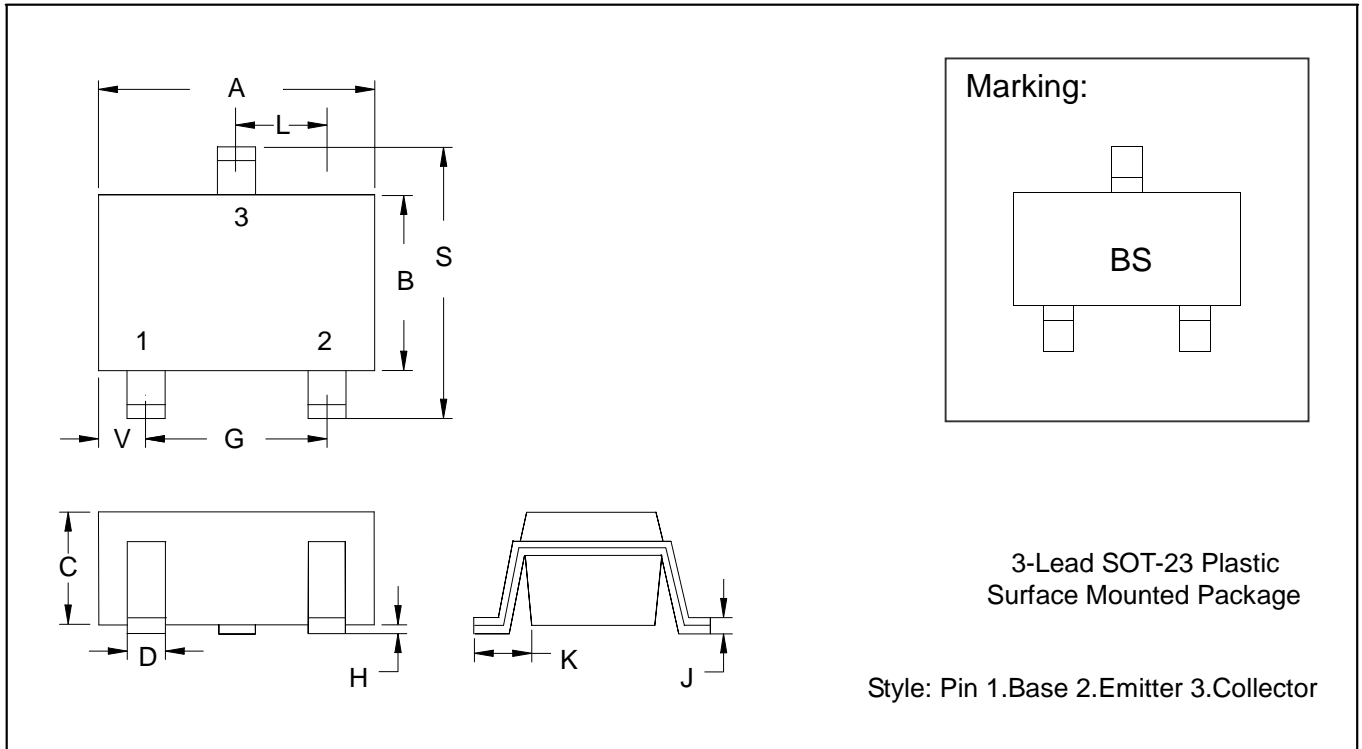
Reel Dimension



Carrier Tape Dimension



SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local Tin Far sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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